SMD
POWER INDUCTORS

MODEL NO. : SMI-75 SERIES (CD75 COMPATIBLE)

FEATURES:

* SUPERIOR QUALITY FROM AN AUTOMATED PRODUCTION LINE.
* PICK AND PLACE COMPATIBLE.
* TAPE AND REEL PACKING.

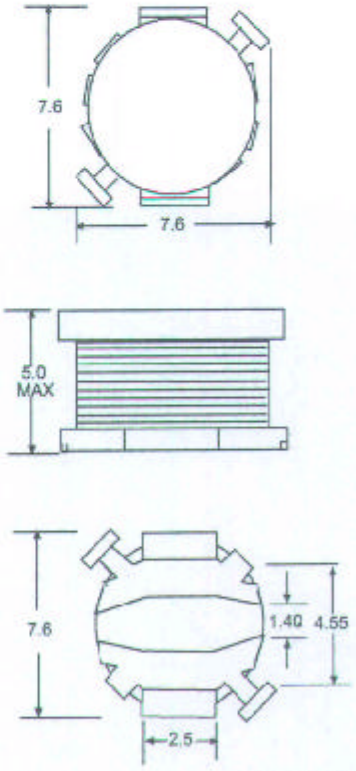
APPLICATION :

* NOTEBOOK COMPUTERS.
* DC-DC CONVERTORS.
* DC-AC INVERTERS.

ELECTRICAL SPECIFICATION:

PART NO.	INDUCTANCE (uH)	D.C.R. MAX (Ω)	RATED CURRENT (A)
SMI-75-100	10	0.07	2.30
SMI-75-120	12	0.08	2.00
SMI-75-150	15	0.09	1.80
SMI-75-180	18	0.10	1.60
SMI-75-220	22	0.11	1.50
SMI-75-270	27	0.12	1.30
SMI-75-330	33	0.13	1.20
SMI-75-390	39	0.16	1.10
SMI-75-470	47	0.18	1.00
SMI-75-560	56	0.24	0.94
SMI-75-680	68	0.28	0.85
SMI-75-820	82	0.37	0.78
SMI-75-101	100	0.43	0.72
SMI-75-121	120	0.47	0.66
SMI-75-151	150	0.64	0.58
SMI-75-181	180	0.71	0.51
SMI-75-221	220	0.96	0.49
SMI-75-271	270	1.11	0.42
SMI-75-331	330	1.26	0.40
SMI-75-391	390	1.77	0.36
SMI-75-471	470	1.96	0.34

PHYSICAL DIMENSION : (UNIT:mm)

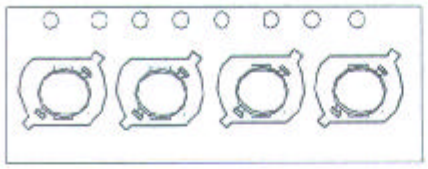


TOLERANCE: ±0.3

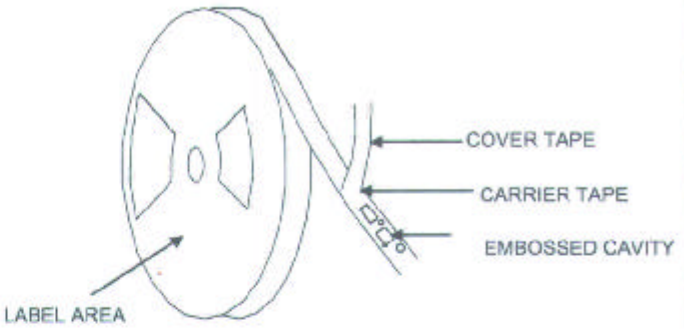
NOTE(1):TEST FREQUENCY: 100KHz,1VRMS.
NOTE(2):10~470uH ±10%.
NOTE(3):THIS INDICATES THE VALUE OF CURRENT WHEN THE INDUCTANCE IS 10% LOWER THAN ITS INITIAL VALUE AT D.C. CURRENT WHEN AT ΔT=40°C WHICHEVER IS LOWER.

PACKING

Tape and Reel Orientation



USER DIRECTION OF FEED



NOTE : Top view shown with cover tape removed.

TAPE WIDTH	REEL WIDTH	COMPONENT PITCH	UNITS PER REEL
16mm	22.4mm	12mm	1000

TAPE SPECIFICATIONS:
- Carrier Tape Type : Conductive.
- Cover Tape Type : Antistatic.
- Cover Tape Adhesion to Carrier : 10 - 70 grams.

REEL SPECIFICATIONS:
- Diameter (flange) : 13" (330.2mm)

STANDARDS : All embossed carrier tape packaging will be accomplished in compliance with latest revision of EIA-481 "Taping of surface Mount Components for Automatic Placement".

ENVIRONMENTAL PERFORMANCE

ITEM	TEST	CONDITION
1	Thermal Shock	One cycle shall consist of: (1) 30minutes at temperature -30°C (2) 15 seconds maximum at room ambient. (3) 30 minutes at temperature +85°C (4) 15 seconds maximum at room ambient. Subject samples to 10 cycles. Test per applicable devices specification after a 4 hours stabilization at room ambient.
2	Vibration	Inductance deviation within ±3.0% after vibration for 1 hour. In each of three orientations at sweep vibration (10~50~10Hz) with 1.5mm P-P amplitude.
3	Solderability	Solder pot at 230°C±5°C, with kester 1544 solder flux. Dip parts into solder pot containing 63/37 molten alloy for 5 second±1 second. Wetting must occur on a minimum of 90% of the terminations.
4	Operating Temperature	-25°C ~ +80°C (coil contain heat)
5	Humidity	Inductance deviation within±5.0% After 96 hour in 90~95% relative humidity at 40±2°Cand 1 hour drying under normal condition.
6	Mechanical Shock	Inductance deviation within ±5.0% after drop down with 981m/s^2 (100G)shock. Attitude upon a rubber block method shock testing machine, for 1 time, in each of three orientations.